



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾

Supply Voltage:	–0.5V to 3.6V
Input Voltage (all inputs)	–0.3V to $V_{CC}+0.3V$
Output Current	28mA
Storage Temperature Range	–65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (Soldering 4 Sec)	+260°C
Package Thermal Resistance θ_{JA} 16-pin WQFN θ_{JC} 16-pin WQFN	+78.9°C/W +42.7°C/W
ESD Rating (HBM)	5kV
ESD Rating (MM)	250V

- (1) Absolute Maximum Ratings are those parameter values beyond which the life and operation of the device cannot be ensured. The stating herein of these maximums shall not be construed to imply that the device can or should be operated at or beyond these values. The table of [Electrical Characteristics](#) specifies acceptable device operating conditions.

Recommended Operating Conditions

Supply Voltage ($V_{CC} - V_{EE}$):	3.3V $\pm 5\%$
Operating Free Air Temperature (T_A)	–40°C to +85°C

DC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified ⁽¹⁾⁽²⁾.

Parameter	Test Conditions	Reference	Min	Typ	Max	Unit
V_{CMIN}	Input Common Mode Voltage	SDI, \overline{SDI}	$1.6 + V_{SDI}/2$		$V_{CC} - V_{SDI}/2$	V
V_{SDI}	Input Voltage Swing		100		2000	mV _{P-P}
V_{CMOUT}	Output Common Mode Voltage	SDO, \overline{SDO}		$V_{CC} - V_{SDO}$		V
V_{SDO}	Output Voltage Swing		750	800	850	mV _{P-P}
			900	1000	1100	mV _{P-P}
I_{CC}	Supply Current			⁽³⁾ 38	43	mA

- (1) Current flow into device pins is defined as positive. Current flow out of device pins is defined as negative. All voltages are stated referenced to $V_{EE} = 0$ Volts.
 (2) Typical values are stated for $V_{CC} = +3.3V$ and $T_A = +25^\circ C$.
 (3) Maximum I_{CC} is measured at $V_{CC} = +3.465V$ and $T_A = +70^\circ C$.

AC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified ⁽¹⁾.

Parameter	Test Conditions	Reference	Min	Typ	Max	Unit
DR _{SDI}	Input Data Rate	⁽²⁾ SDI, $\overline{\text{SDI}}$			540	Mbps
t _{jit}	Additive Jitter	270 Mbps		18		pSp.p
t _r , t _f	Output Rise Time, Fall Time	20% – 80%	400	560	800	ps
	Mismatch in Rise/Fall Time	⁽²⁾			30	ps
	Duty Cycle Distortion	⁽²⁾			100	ps
t _{OS}	Output Overshoot	⁽²⁾			8	%
RL _{SDO}	Output Return Loss		⁽³⁾ 15	20		dB

(1) Typical values are stated for V_{CC} = +3.3V and T_A = +25°C.

(2) Specification is ensured by characterization.

(3) Output return loss is dependent on board design. The LMH0001 meets this specification on the SD001SQ evaluation board from 5MHz to 1.5GHz.

CONNECTION DIAGRAM

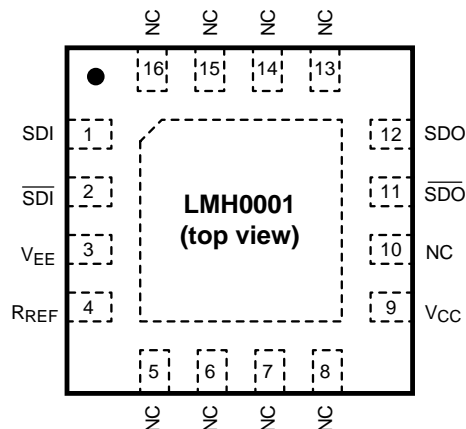


Figure 1. 16-Pin WQFN Package
See Package Number RUM0016A

PIN DESCRIPTIONS

SOIC Pin No.	WQFN Pin No.	Name	Description
1	1	SDI	Serial data true input.
2	2	$\overline{\text{SDI}}$	Serial data complement input.
3	3	V _{EE}	Negative power supply (ground).
4	4	R _{REF}	Output driver level control. Connect a resistor to V _{CC} to set output voltage swing.
5	9	V _{CC}	Positive power supply (+3.3V).
7	11	$\overline{\text{SDO}}$	Serial data complement output.
8	12	SDO	Serial data true output.
—	5, 6, 7, 8, 10, 13, 14, 15, 16	NC	No connect.
—	DAP	V _{EE}	Connect exposed DAP to negative power supply (ground).

DEVICE OPERATION

INPUT INTERFACING

The LMH0001 accepts either differential or single-ended input. The inputs are self-biased, allowing for simple AC or DC coupling. DC-coupled inputs must be kept within the specified common-mode range. $\overline{\text{SDI}}$ and $\overline{\text{SDI}}$ are self-biased at approximately 2.1V with $V_{CC} = 3.3\text{V}$. Figure 2 shows the differential input stage for $\overline{\text{SDI}}$ and $\overline{\text{SDI}}$.

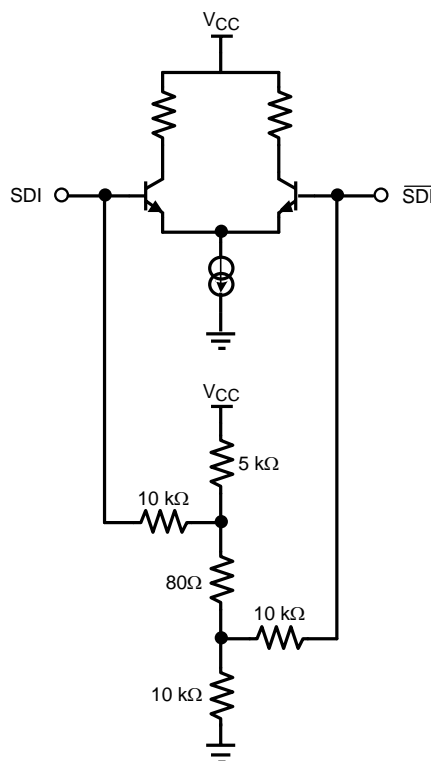


Figure 2. Differential Input Stage for $\overline{\text{SDI}}$ and $\overline{\text{SDI}}$.

OUTPUT INTERFACING

The LMH0001 uses current mode outputs. Single-ended output levels are 800 mV_{P-P} into 75Ω AC-coupled coaxial cable (with $R_{REF} = 750\Omega$). Output level is controlled by the value of the R_{REF} resistor connected between the R_{REF} pin and V_{CC} .

The R_{REF} resistor should be placed as close as possible to the R_{REF} pin. In addition, the copper in the plane layers below the R_{REF} network should be removed to minimize parasitic capacitance.

REVISION HISTORY

Changes from Revision B (April 2013) to Revision C

Page

- Changed layout of National Data Sheet to TI format 4

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LMH0001SQ/NOPB	ACTIVE	WQFN	RUM	16	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L001	Samples
LMH0001SQE/NOPB	ACTIVE	WQFN	RUM	16	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L001	Samples
LMH0001SQX/NOPB	ACTIVE	WQFN	RUM	16		TBD	Call TI	Call TI	-40 to 85	L001	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMH0001SQ/NOPB	WQFN	RUM	16	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LMH0001SQE/NOPB	WQFN	RUM	16	250	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

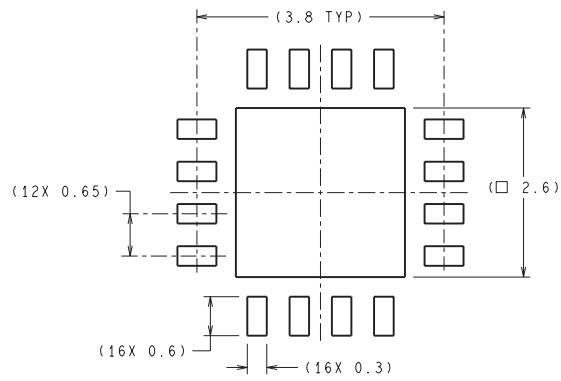
TAPE AND REEL BOX DIMENSIONS



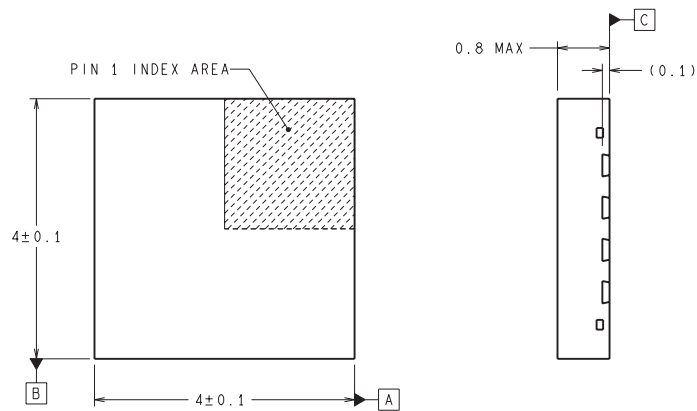
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMH0001SQ/NOPB	WQFN	RUM	16	1000	210.0	185.0	35.0
LMH0001SQE/NOPB	WQFN	RUM	16	250	210.0	185.0	35.0

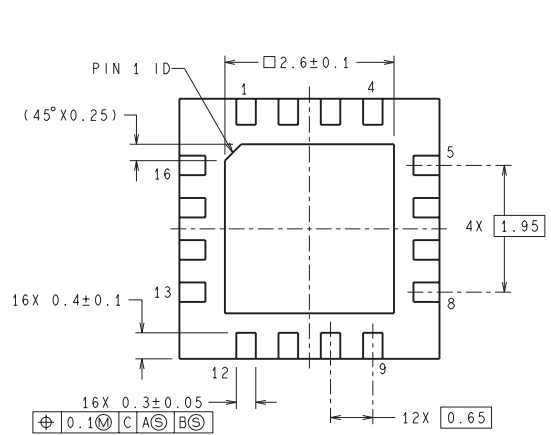
RUM0016A



RECOMMENDED LAND PATTERN



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SQB16A (Rev A)

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